Notes:

"DNP" = "Do Not Populate"

DNP R52, R62, C42, C58 and insert D100...D103

Disconnect pin 3 of U8 and route an external wire, far from switch-nodes, to pin 12 of U3

Add on BOM 2 x SFP074-70x20x10mm thermal blocks from Fischer + screws + sil-pads

Add on BOM 2 x ML26AAG heatsinks from Aavid + screws + washers

Add 0.5mm...1mm insulating washer underneath Q10, Q12 and HS1-shunt to increase clearance to PCB
J4 --> short = LLC OFF

Place R27 and C17 close to pin 6 and 12 of U3
Disconnect pin 3 of U8 and route an external wire, far from switch-nodes, to pin 12 of U3

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